

2. (Amended) The interconnect substrate as defined in claim 1, wherein:  
the second substrate is larger than the first substrate, and  
a whole surface of the first substrate is adhered to the second substrate.
3. (Amended) The interconnect substrate as defined in claim 1, wherein:  
the first interconnect pattern is formed on a first surface of the first substrate;  
the second interconnect pattern is formed on a second surface of the second  
substrate; and  
a third surface of the first substrate opposite to the first surface and the second  
surface of the second substrate are disposed to oppose each other.

Please add new claims 40 and 41 as follows:

- 40. (New) The interconnect substrate as defined in claim 1, further comprising:  
an adhesive disposed between the first and second substrates.--
- 41. (New) The interconnect substrate as defined in claim 5, wherein the  
conductive material projects from the third surface of the first substrate.--

#### REMARKS

Claims 1-41 are pending. By this Amendment claims 1-3 are amended and claims 40-41 are added. No new matter is added by any of these amendments.

Reconsideration based on the following remarks is respectfully requested.

The attached Appendix includes a marked-up copy of each rewritten claim (37 CFR §1.121(c)(1)(ii)).

#### **I. Rejoinder of Claims 1-39 from Restriction/Election of Species Requirement**

The Office Action makes final the August 23, 2002 Election of Species Requirement. Accordingly, Applicant respectfully requests rejoinder of claims 6 and 9-39, as at least claims 1 and 14 are generic.